

Bill of Materials

TI DESIGNS

TIDM-BPM

Item	Qty	Reference	Value	Part Description	PCB Footprint
1	1	B1	none	BUTTON-4P	SW-4P
2	4	B2, B3, B4, B5	none	BUTTON-4P	SW-4P
3	1	buzzer	none	buzzer	buzzer
4	1	C1	0.47uF	CAP	C/0805/SMT1
5	1	C2	47uF	CAP	C/0805/SMT1
6	2	C3, C17	0.01uF	CAP	C/0805/SMT1
7	1	C4	0.1uF	CAP	C/0805/SMT1
8	2	C5, C7	4.7uF	CAP, CAP/0805	C/0805/SMT1
9	1	C6	10nF	CAP	C/0805/SMT1
10	1	C8	47pF	CAP	C/0805/SMT1
11	1	C9	10uF	CAP	C/0805/SMT1
12	1	C10	0.01uF	CAP	C/0805/SMT1
13	4	C11, C12, C15, C18	1uF	CAP	C/0805/SMT1
14	2	C14, C19	12pF	CAP	C/0805/SMT1
15	1	C16	1uF	CAP	C/0805/SMT1
16	1	C20	470pF	CAP	C/0805/SMT1
17	1	C21	4.7nF	CAP/0805	C/0805/SMT1
18	1	C22	470nF	CAP/0805	C/0805/SMT1
19	1	CON1	none	CON20*2P	LCD1

Item	Qty	Reference	Value	Part Description	PCB Footprint
20	3	D1, D2, D3	MBRA320	DIODE	DIODE
21	1	H1	none	HEADER10P	CN10P/2.54
22	1	H2	none	header-4p	CON4P-2.54H
23	2	JUMP1, JUMP2	none	JUMP-3P	CON3P-2.54H
24	2	LED1, LED2	none	LED_1	LED0805
25	1	P1	none	BAT	CON3P-2.54H
26	3	Q1, Q2, Q3	'NSS4020	NPN_BJT	SOT23-3P
27	1	R1	300K	RES	R/0805/SMT1
28	3	R2, R3, R15	47R	RES	R/0805/SMT1
29	1	R4	47K	RES	R/0805/SMT1
30	3	R5, R13, R29	200K	RES	R/0805/SMT1
31	3	R6, R11, R12	1K	RES	R/0805/SMT1
32	1	R7	2K	RES	R/0805/SMT1
33	1	R8	800K	RES	R/0805/SMT1
34	9	R9, R22, R25, R33, R34, R35, R36,	100k	RES	R/0805/SMT1
35	1	R10	1R	RES	C/0805/SMT1
36	3	R14, R16, R20	0R	RES	R/0805/SMT1
37	2	R18, R19	33k	RES	R/0805/SMT1
38	2	R21, R23	1.5K	RES	R/0805/SMT1
39	6	R24, R27, R28, R30, R31, R32	500k	RES	R/0805/SMT1
40	1	R26	61.9k	RES	R/0805/SMT1
41	2	R37, R38	0R	RES	R/0805/SMT1
42	1	R41	0R	RES/0805	C/0805/SMT1
43	1	U1	TPS763XX	TPS763XX	SOT23-5P
44	1	U2	LMV324	LMV324	SO-G14/G3.3
45	1	U3	430100PIN_F6638	430100PIN	IC-LQFP100-PZ - duplicate
46	1	U4	MP3V5050	MP3V5050	MP3V5050
47	1	U6	CAT24C32	CAT24C32	SO-G8/D7.7
48	3	U7, U8, U9	CON2	CON2	CON2P-2.54H
49	1	U11	BP300	BP300	BP300UF
50	1	Y1	32kHz	CRYSTAL	XIAL-2*5V

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